# 8-bit Proprietary Microcontrollers

CMOS

# F<sup>2</sup>MC-8L MB89051 Series

# MB89F051/MB89051

## DESCRIPTION

The MB89051 series is a general-purpose, single-chip microcontroller that features a compact instruction set and contains a range of peripheral function set and timers, serial interface, a PWM timer, the USB hub function and the USB function. The USB hub function, in particular, supports five down ports (one of them is dedicated to an internal function) allowing them to interface with other USB devices. The microcontrollers also contain one USB function channel to support full speed.

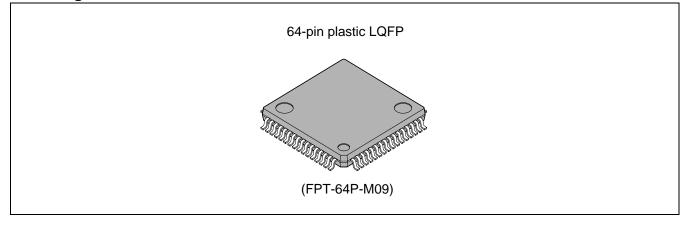
# FEATURES

#### • Package type 64-pin LQFP Package (0.65 mm pitch)

 High-speed operations at low voltage Minimum execution time : 0.33 μs (Automatically generates a 12 MHz main clock and a 48 MHz USB interface synchronization clock with an externally supplied 6 MHz clock and the internal PLL circuit.)

(Continued)

### Package





- F<sup>2</sup>MC-8L CPU core Instruction set that is optimum to the controllers -Multiplication and division instructions -16-bit arithmetic operations -branch instructions by bit testing -bit manipulation instructions, etc. PLL clock control The internal PLL clock circuit allows the use of low-speed clocks which are advantageous to noise characteristics. (6 MHz externally-supplied clock→12 MHz internal system clock) · Various timers 8-bit PWM timer (can be used as either 8-bit PWM timer 2 channels or PPG timer 1 channel) Internal 21-bit timebase timer • Internal USB transceiver circuit (Compatible with full and low speeds) USB hub USB function Compliant to USB Protocol Revision 1.0 Five downstream port channels (One of these channels is dedicated to a function.) Automatically responds to all USB protocols by hardware. Descriptor configuration is provided as ROM data for automatic responding by hardware (Vender ID and product ID). String data is not supported. Allows switching between BUS power supply and own power supply mode. Power supply to the USB down port is controlled port by port. USB function USB function Compliant to USB Protocol Revision 1.0 Support for full speed when using hub Support for both low and full speeds when using function Allows four endpoints to be specified at maximum. Types of transfer supported: control/interrupt/bulk/isochronous Built-in DMAC (Maps the buffer for each endpoint on to the internal RAM to directly access the memory for function's send and receive data.) UART/SIO, SIO Serial Interface Built-in UART/SIO function (selectable by switching)  $\times$  1 channel Built-in SIO (3.3 V) × 2 channels I<sup>2</sup>C interface\*1 Supports Philips I<sup>2</sup>C bus standards Uses a two-wire data transfer protocol Master/slave send/receive External interrupt External interrupt (level detection  $\times$  7 channels) Seven inputs are independent of one another and can also be used for resetting from low-power consumption mode (the L-level detection feature available). Clock output functions Able for 12 MHz<sup>\*2</sup> and 6 MHz<sup>\*2</sup> clocks to output. (dedicated pins, 3 V) • Low power consumption (standby mode supported)
- Stop mode (There is almost no current consumption since oscillation stops.) Sleep mode (This mode stops the running CPU.)

- (Continued)
  - A maximum of 41 general-purpose I/O ports General-purpose I/O ports (CMOS) : 37 (7 of 3 V ports) General-purpose I/O ports (Nch open drain) : 4
  - Power supply Supply voltage: 3.3 V  $\pm$  0.3 V or 5.0 V  $\pm$  0.5 V
  - Operating temperature  $T_A = -40$  ° to +85 °C (When the USB function is not in use.)  $T_A = 0$  °C to +70 °C (When the USB function is in use.)
- \*1 : I<sup>2</sup>C license

The customer is licensed to use Philips I<sup>2</sup>C patent when using this product in an I<sup>2</sup>C system that complies with the Philips I<sup>2</sup>C standard specifications.

\*2 : When an external supply clock is at 6 MHz.

# ■ PRODUCT LINEUP

/	Part	number	MB89051	MB89F051						
Pa	rameter		MID09051	MID03FU3T						
RC	OM size		32 KB	32 KB (FLASH)						
RA	M size			2 KB						
Pa	ckage		LQFP-64 (	FPT-64P-M09)						
Ot	hers		MASK product	FLASH product/EVA product						
CF	PU functi	ons	Number of instructions: 136Instruction bit length: 8 bitsInstruction length: 1 to 3 bytesData bit length: 1, 8, and 16 IMinimum execution time: 0.33 µs (6 MIInterrupt processing time: 3 µs (6 MHz)	Hz)						
	Genera purpose		General purpose I/O ports (37 : CMOS (7 of 3 V ports ) , 4 : Nch open drain)							
USB hub			Upstream port : 1 channel Downstream port : 5 channels (One is dedicated to an internal function.) Port power supply control method : By individual port Allows selection between own power supply and bus power supply							
Peripheral functions	USB fu	nction	Supports full speed : when using hub Supports full and low speeds : when using function End point max 4 Built-in DMAC (Can be set to DMA transfer to the internal RAM)							
eral	PWM ti	mer	8-bit PWM timer operation 2 channels (can also be used as a PPG 1 channel timer)							
Periph	UART	SIO	Allows switching between UART (clock-syn and SIO (simple serial transfer).	chronous/asynchronous data transfer allowed)						
	SIO		SIO (simple serial) $\times$ 2 channels (3 V)							
	I <sup>2</sup> C inte	rface	One channel. Supports Phillips I <sup>2</sup> C bus stand with other devices.	lards. Uses a 2-wire protocol for communications						
	Timeba timer	ISE	21-bit timebase timer							
	Clock o	output	Allows clock output of 12 MHz* and 6 MHz*	(3 V)						
Sta	andby m	ode	Sleep mode and Stop mode							

\* : When external supply clock is at 6 MHz.

# DIFFERENCES AMONG PRODUCTS

#### 1. Memory Size

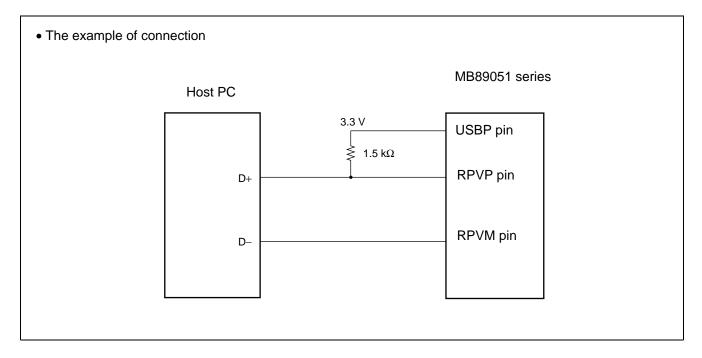
• Before evaluating using the FLASH product, it is necessary to confirm its differences from the product that will actually be used.

### 2. Current Consumption

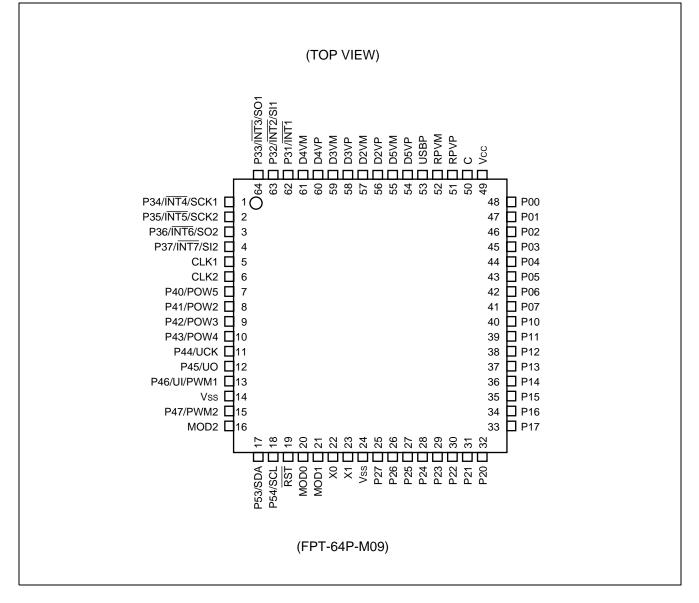
- When operating at low speed, FLASH products will consume more current than mask ROM products. However, in sleep/stop mode the current consumption is the same.
- For detailed information on each package, see "■PACKAGE DIMENSIONS"

### 3. USB Pull-up Resistor control

• Remains in high impedance state until USB connection take place. Before the USB connection, use USBP pin output to control pull-up resistance by software.



### ■ PIN ASSIGNMENT



# ■ PIN DESCRIPTION

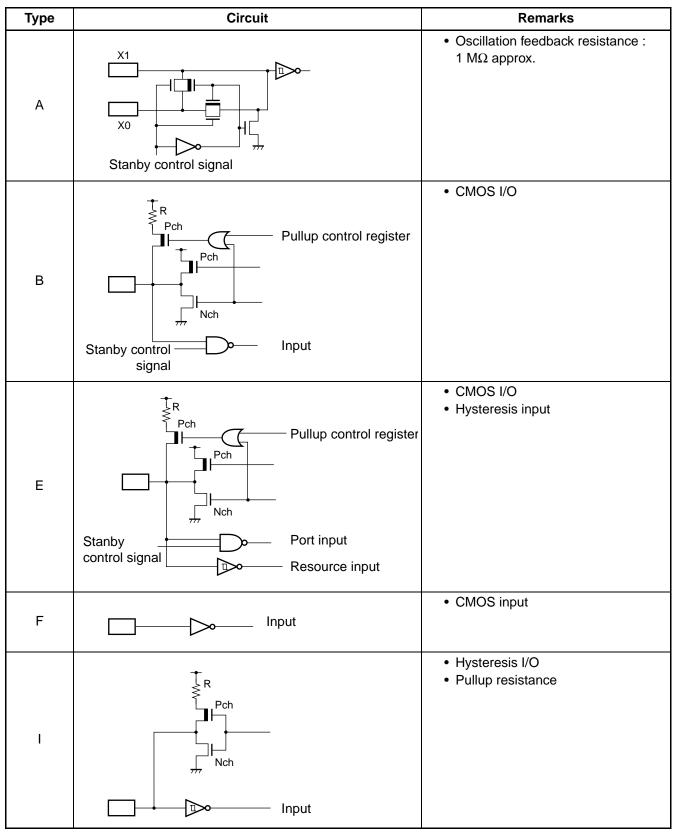
Pin No.	Pin name	Circuit type	Function
1	P34/INT4/ SCK1	Е	General-purpose CMOS I/O pin The external interrupt input is a hysteresis input. (Level detection) SIO1 clock I/O
2	P35/INT5/ SCK2	Е	General-purpose CMOS I/O pin The external interrupt input is a hysteresis input. (Level detection) SIO2 clock I/O
3	P36/INT6/ SO2	В	General-purpose CMOS I/O pin The external interrupt input is a hysteresis input. (Level detection) SIO2 serial data output
4	P37/INT7/SI2	Е	General-purpose CMOS I/O pin The external interrupt input is a hysteresis input. (Level detection) SIO2 serial data input
5	CLK1	М	6 MHz clock output pin (When external supply clock is at 6 MHz.)
6	CLK2	М	12 MHz clock output pin (When external supply clock is at 6 MHz.)
7	P40/POW5	В	General-purpose CMOS I/O pin This pin also serves as USB Down Port power control signal.
8	P41/POW2	В	General-purpose CMOS I/O pin This pin also serves as USB Down Port power control signal.
9	P42/POW3	В	General-purpose CMOS I/O pin This pin also serves as USB Down Port power control signal.
10	P43/POW4	В	General-purpose CMOS I/O pin This pin also serves as USB Down Port power control signal.
11	P44/UCK	Е	General-purpose CMOS I/O pin UART/S10 clock I/O
12	P45/UO	В	General-purpose CMOS I/O pin UART/S10 serial data output
13	P46/UI/ PWM1	Ν	Nch open drain general-purpose I/O pin UART/S10 serial data input PWM timer
14	Vss		Power supply pin (GND)
15	P47/PWM2	К	Nch open drain general-purpose I/O pin PWM timer
16	MOD2	F	An operating mode designation pin. Connect directly to Vss.
17	P53/SDA	К	Nch open drain general-purpose I/O pin Also serve as I²C interface data input/output pin.
18	P54/SCL	К	Nch open drain general-purpose I/O pin Also serve as I²C interface clock input/output pin.
19	RST	I	Reset pin (Reset on the negative logic low level.)
20	MOD0	F	An operating mode designation pin. Connect directly to Vss.
21	MOD1	F	An operating mode designation pin. Connect directly to Vss.

Pin No.	Pin name	Circuit type	Function
22	X0	^	Ding for the connection of envetal application circuit (C MHz)
23	X1	A	Pins for the connection of crystal oscillation circuit.(6 MHz)
24	Vss		Power supply pin (GND)
25	P27	В	General-purpose CMOS I/O pin*
26	P26	В	General-purpose CMOS I/O pin*
27	P25	В	General-purpose CMOS I/O pin*
28	P24	В	General-purpose CMOS I/O pin*
29	P23	В	General-purpose CMOS I/O pin*
30	P22	В	General-purpose CMOS I/O pin*
31	P21	В	General-purpose CMOS I/O pin*
32	P20	В	General-purpose CMOS I/O pin*
33	P17	В	General-purpose CMOS I/O pin
34	P16	В	General-purpose CMOS I/O pin
35	P15	В	General-purpose CMOS I/O pin
36	P14	В	General-purpose CMOS I/O pin
37	P13	В	General-purpose CMOS I/O pin
38	P12	В	General-purpose CMOS I/O pin
39	P11	В	General-purpose CMOS I/O pin
40	P10	В	General-purpose CMOS I/O pin
41	P07	В	General-purpose CMOS I/O pin
42	P06	В	General-purpose CMOS I/O pin
43	P05	В	General-purpose CMOS I/O pin
44	P04	В	General-purpose CMOS I/O pin
45	P03	В	General-purpose CMOS I/O pin
46	P02	В	General-purpose CMOS I/O pin
47	P01	В	General-purpose CMOS I/O pin
48	P00	В	General-purpose CMOS I/O pin
49	Vcc		Power supply pin.
50	С	_	Connect an external capacitor of 0.1 $\mu$ F. When using with 3.3 V power supply, connect this pin with the Vcc pin to set to 3.3 V input.
51	RPVP	USBDRV	USB route port + pin
52	RPVM	USBDRV	USB router port – pin
53	USBP	L	USB pull-up resistance connection pin.
54	D5VP	USBDRV	USB down port 5 + pin
55	D5VM	USBDRV	USB down port 5 – pin

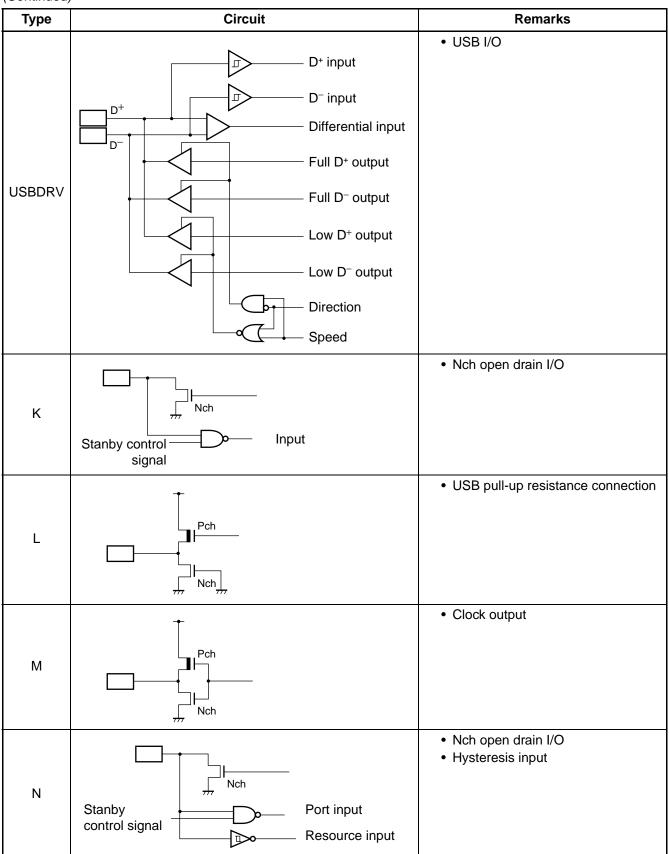
\* : For output only on the emulator.

Pin No.	Pin name	Circuit type	Function					
56	D2VP	USBDRV	USB down port 2 + pin					
57	D2VM	USBDRV	USB down port 2 – pin					
58	58 D3VP USBDRV		USB down port 3 + pin					
59	59 D3VM USBDRV		JSB down port 3 – pin					
60	D4VP	USBDRV	USB down port 4 + pin					
61	D4VM	USBDRV	USB down port 4 – pin					
62	P31/INT1	В	General-purpose CMOS I/O pin External interrupt input (Hysteresis input (level detection) )					
63	P32/INT2/SI1	Е	General-purpose CMOS I/O pin External interrupt input (Hysteresis input (level detection) ) SIO1 serial data input					
64 P33/INT3/ SO1 B		В	General-purpose CMOS I/O pin External interrupt input (Hysteresis input (level detection) ) SIO1 serial data output					

# ■ I/O CIRCUIT TYPE







### ■ HANDLING DEVICES

#### 1. Preventing Latchup

Latchup may occur on CMOS ICs if voltage higher than Vcc or lower than Vss is applied to input or output pins other than the medium- and high-voltage pins or if voltage higher than the rating is applied between Vcc and Vss.

When latchup occurs, power supply current increases rapidly and might thermally damage elements. When using, take great care not to exceed the absolute maximum ratings.

Also take care to prevent the analog input from exceeding the digital power supply (Vcc) when the power supply to the analog power system is turned on and off.

#### 2. Treatment of Unused Input Pins

Leaving unused input pins open could cause malfunctions and latchup leading to permanent damage to the pins. These unused pins should be connected to a pullup or pulldown resistance of at least 2 k $\Omega$  between the pin and the power supply.

Unused I/O pins should be placed in output state to leave it open or pins that are in input state should be handled the same as unused input pins.

### 3. Note to noise in the External Reset Pin (RST)

If the reset pulse applied to the external reset pin ( $\overline{RST}$ ) does not meet the specifications, it may cause malfunctions. Use caution so that the reset pulse less than the specifications will not be fed to the external reset pin ( $\overline{RST}$ ).

#### 4. Power Supply Voltage Fluctuations

Although Vcc power supply voltage is assured to operate within the rated range, a rapid fluctuation of the voltage could cause malfunctions even if it occurs within the rated range. Stabilizing voltage supplied to the IC is therefore important. As stabilization guidelines, it is recommended to control power so that Vcc ripple fluctuations (P-P value) will be less than 10% of the standard Vcc value at the commercial frequency (50 Hz to 60 Hz) and the transient fluctuation rate will be less than 0.1 V/ms at the time of a momentary fluctuation such as when power is switched.

#### 5. Note on the clock during operation

This microcontroller uses a PLL for generating the main clock signal. If the oscillator is removed or the clock input stops during operation, therefor, the microcontroller may keep on operating at the free-running frequency of the self-oscillation circuit in the PLL. The operation is not however guaranteed.

### 6. About port 2 (P20 to P27)

Port 2 serves as an output-only terminal on the emulator.

### PROGRAMMING AND ERASING FLSH MEMORY

### 1. Flash Memory

The flash memory is located between 8000<sub>H</sub> and FFFF<sub>H</sub> in the CPU memory map and incorporates a flash memory interface circuit that allows read access and program access from the CPU to be performed in the same way as mark ROM. Programming and erasing flash memory is also performed via the flash memory interface circuit by executing instructions in the CPU. This enables the flash memory to be updated in place under the control of the CPU, providing an efficient method of updating program and data.

### 2. Flash Memory Features

- 32 Kbyte × 8-bit configuration (16 K + 8 K + 8 K sectors)
- Automatic programming algorithm (Embedded Algorithm\* : Equivalent to MBM29LV200)
- Includes an erase pause and restart function
- Data polling and toggle bit for detection of program/erase completion
- Detection of program/erase completion via CPU interrupt
- Compatible with JEDEC-standard command
- Sector Protection (sectors can be combined in any combination)
- No. of program/erase cycles : 10,000 (Min)
- \* : Embedded Algorithm is a trademark of Advanced Micro Devices.

### 3. Procedure for Programming and Erasing Flash Memory

Programming and reading flash memory cannot be performed at the same time. Accordingly, to program or erase flash memory, the program must first be copied from flash memory to RAM so that programming can be performed without program access from flash memory.

### 4. Flash Memory Register

#### Control status register (FMCS)

Address	bit7	bit6	bit5	bit4	bit3	bit2	bit1	bit0	Initial value
002Ен	INTE	RDYINT	WE	RDY	Re- served	Re- served	_	Re- served	000Х00Х0в
	R/W	R/W	R/W	R	R/W	R/W	_	R/W	

### 5. Sector Configuration

The table below shows the sector configuration of flash memory and lists the addresses of each sector for both during CPU access and a flash memory programming.

• Sector configuration of flash memory

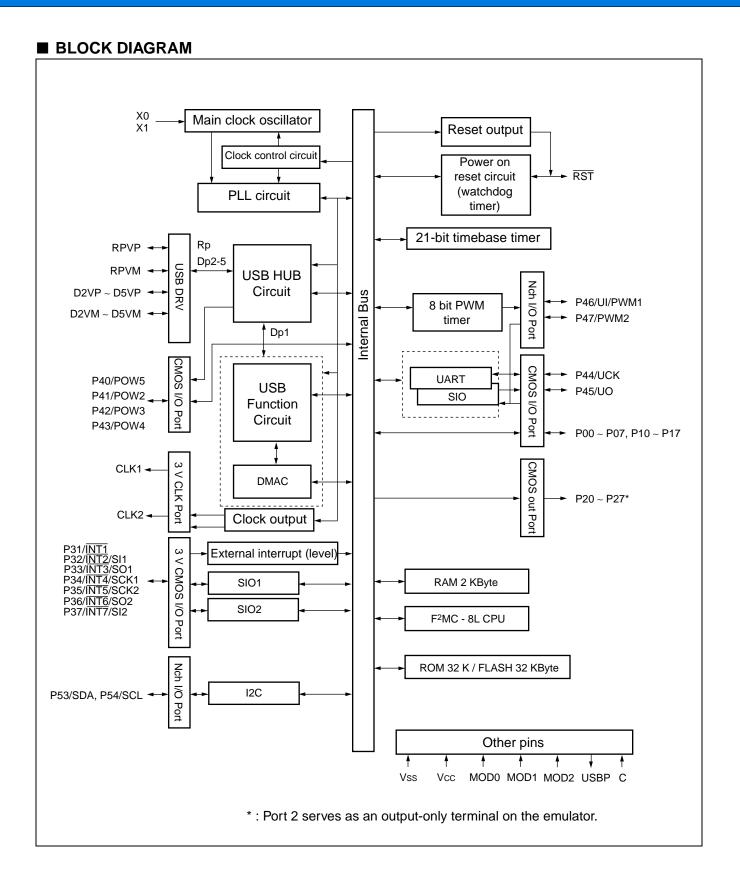
Flash Memory	CPU Address	Programmer Address*
16 Kbytes	FFFF <sub>H</sub> to C000 <sub>H</sub>	1FFFFн to 1C000н
8 Kbytes	BFFFH to A000H	1BFFFн to 1A000н
8 Kbytes	9FFFн to 8000н	19FFFн to 18000н

\* : Programmer address

The programmer address is the address to be used instead of the CPU address when programming data from a parallel flash memory programmer. Use the programmer address on programming or erasing using a general-purpose parallel programmer.

# 6. ROM Programmer Adaptor and Recommended ROM Programmers

Package	Compatible adapter	Compatible programmers and models Ando Denki K.K.				
rackaye	Sunhayato Corp.					
FPT-64P-M09	FLASH-64QF2-32DP-8LF3	AF9708 (ver 1.60 or higher) AF9709 (ver 1.60 or higher)				
<ul> <li>Inquiry: Sunhayato Corp.</li> </ul>	: TEL : 81-3-3984 FAX : 81-3-3971 E-mail : adapter@s	-0535				
Ando Denki K. K.	: TEL : 81-3-3733	-1160				



# CPU CORE

#### 1. Memory Size

The MB89051 microcontroller offers a memory space of 64 Kbytes consisting of the I/O, RAM and ROM areas. The memory space contains areas that are used for specific purposes, such as a general-purpose register and a vector table.

• I/O area (addresses: 0000H through 007FH)

This area is assigned with the control and data registers, for example, of peripheral functions to be built in. The I/O area is as accessible as the memory since the area is assigned to a part of the memory space.Direct addressing also allows the area to be accessed faster.

• RAM area

As an internal data area, a static RAM is built in.

The internal RAM capacity varies with the product type.

The area  $80_{\text{H}}$  to FF<sub>H</sub> can be accessed at high speed with direct addressing.

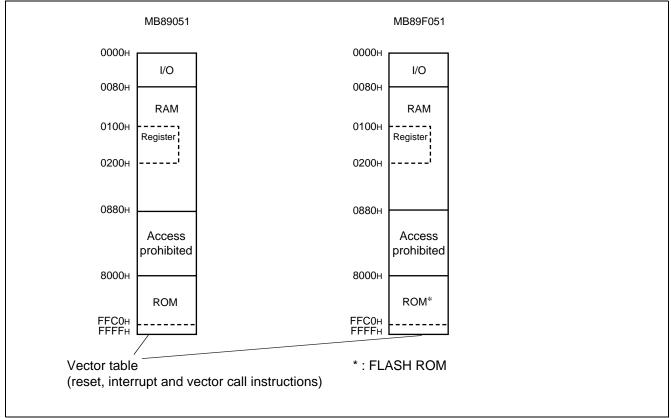
The area 100H to 1FFH can be used a general-purpose register area. (The usable area is limited depending on the product.)

When reset, RAM data becomes undefined.

ROM area

As an internal program area, a ROM is built in. The internal RAM capacity varies with the product type. The area FFC0 $_{\rm H}$  to FFFF $_{\rm H}$  should be used for a vector table, for example.

#### Memory map

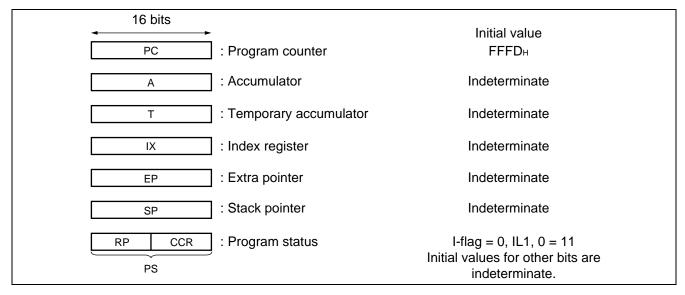


### 2. Registers

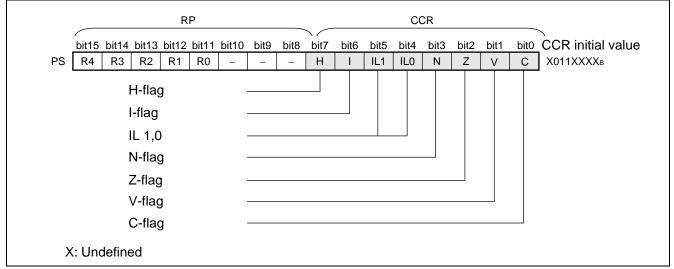
The MB89051 series has two types of registers; the registers dedicated to specific purposes in the CPU and the general-purpose registers.

The dedicated registers are as follows:

Program counter (PC)	: A 16-bit register to indicate locations where instructions are stored.
Accumulator (A)	A 16-bit register for temporary storage of operations. In the case of an 8-bit data processing instruction, the lower one byte is used.
Temporary accumulator (T)	A 16-bit register which performs operations with the accumulator. In the case of an 8-bit data processing instruction, the lower one byte is used.
Index register (IX)	: A 16-bit register for index modification.
Extra pointer (EP)	: A 16-bit register to point to a memory address.
Stack pointer (SP)	: A 16-bit register to indicate a stack area.
Program status (PS)	: A 16-bit register to store a register pointer or a condition code.



The PS register can further be divided into the register bank pointer in the higher 8 bits (RP) and the condition code register in the lower 8 bits (CCR). (See the diagram below.)



The RP points to the address of the register bank currently in use. The relationship between the pointer contents and the actual address is based on the conversion rule shown next.

									RP higher bits			OP code lower bits				
	"0"	"0"	"0"	"0"	"0"	"0"	"0"	"1"	R4	R3	R2	R1	R0	b2	b1	b0
	<u> </u>	ŧ	ŧ	ŧ	¥	¥	ŧ	+	ŧ	¥	ŧ	ŧ	¥	ŧ	ŧ	+
Generated address	A15	A14	A13	A12	A11	A10	A9	A8	A7	A6	A5	A4	A3	A2	A1	A0

The CCR consists of the bits indicating arithmetic operation results or transfer data contents and the bits that control CPU operations at the time of an interrupt.

- H flag : The flag is set to "1" when an arithmetic operation results in a carry from bit 3 to bit 4 or in a borrow from bit 4 to bit 3. The bit is cleared to "0" in other instances. The flag is for decimal adjustment instructions; do not use for other than additions and subtractions.
- I flag : Interrupt is enabled when this flag is set to "1." Interrupt is disabled when this flag is set to "0." The flag is set to "0" when reset.
- IL1, 0 Indicates the level of the interrupt currently enabled. An interrupt is processed only if its level is higher than the value this bit indicates.

IL1	IL0	Interrupt level	High-low
0	0	1	Higher
0	1	I	<b>†</b>
1	0	2	↓
1	1	3	Lower = no interruption

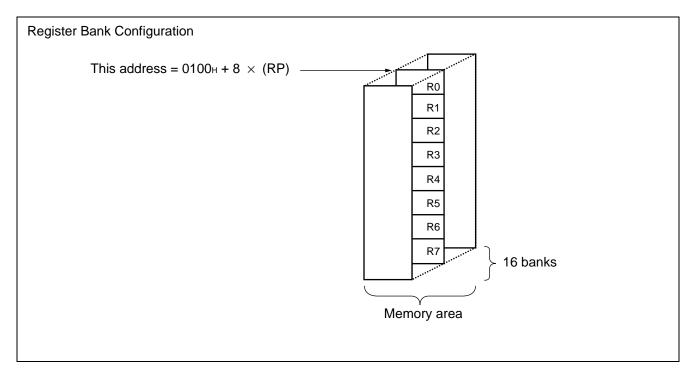
- N flag : The flag is set to "1" when an arithmetic operation results in setting of the MSB to "1" or is cleared to "0" when the MSB is set to "1."
- Z flag : The flag is set to "1" when an arithmetic operation results in "0" or is set to "0" in other instances.
- V flag : The flag is set to "1" when an arithmetic operation results in two's complement overflow or is cleared to "0" if no overflow occurs.
- C flag : The flag is set to "1" when an arithmetic operation results in a carry from bit 7 or in a borrow to bit 7. The flag is cleared to "0" if neither of them occurs. In the case of a shift instruction, the flag is set to the shift-out value.

The following general-purpose registers are provided:

•General-purpose registers : 8-bit data storage registers

The general-purpose registers are 8 bits in length and located in the register banks in the memory. One bank contains eight registers and the MB89051 microcontrollers allow a total of 16 banks to be used at maximum.

The bank currently in use is indicated by the register bank pointer (RP).



# ■ I/O MAP

Address	Register name	Register description	Read/write	Initial value				
00н	PDR0	Port 0 data register	R/W	XXXXXXXX				
01н	DDR0	Port 0 direction register	W	00000000				
02н	PDR1	Port 1 data register	R/W	XXXXXXXX				
03н	DDR1	Port 1 direction register	W	00000000				
04н	PDR2	Port 2 data register	R/W	00000000				
05н		Reserved area						
06н	DDR2	Port 2 direction register	R/W	00000000				
07н	SYCC	System clock control register	R/W	XXX11X00				
08н	STBC	Standby control register	R/W	0 0 0 1 XXXX				
09н	WDTC	Watchdog timer control register	R/W	XXXXXXXX				
0Ан	TBTC	Timebase timer control register	Timebase timer control register R/W					
0Вн		Vacancy	•					
0Сн	PDR3/USBP	Port 3 data register/Pull-up register for USB	R/W	XXXXXXXX				
0Dн	DDR3/USBPC	SBPCPort 3 data direction register/ Pull-up control register for USBR/W						
0Ен		Reserved area	•					
0 <b>F</b> н		Vacancy						
10н	PDR4	Port 4 data register	R/W	XXXXXXXX				
11н	DDR4	Port 4 direction register	R/W	00000000				
<b>12</b> н	PDR5	Port 5 data register	R/W	XXX 1 1 XXX				
13н to 15н		Reserved area						
16н to 20н		Vacancy						
21н	PURR0	Port 0 pullup option setting register	R/W	11111111				
22н	PURR1	Port 1 pullup option setting register	R/W	11111111				
23н	PURR2	Port 2 pullup option setting register	R/W	11111111				
24н	PURR3	Port 3 pullup option setting register	R/W	111111X				
25н	PURR4	Port 4 pullup option setting register	R/W	11111111				
26н		Reserved area						
27н	CTR1	PWM control register 1	R/W	00000000				
28н	CTR2	PWM control register 2	R/W	000X0000				
29н	CTR3	PWM control register 3	R/W	X 0 0 0 XXXX				
2Ан	CMR1	PWM compare register 1	W	XXXXXXXX				
2Вн	CMR2	PWM compare register 2	W	XXXXXXXX				
2Сн	CKR	Clock output control register	R/W	XXXXXXX 0 0				
2Dн	SCS	Serial clock switching register	R/W	XXXXXXX 0				

Address Register name		Register description	Read/write	Initial value		
2Eн	FMCS	Flash memory control status register (Only built-in Flash Memory products)	R, R/W	0 0 0 X 0 0 X 0		
2 <b>F</b> н	SMC1	Serial mode control register 1	R/W	00000000		
30н	SMC2	Serial mode control register 2	00000000			
31н	SSD	Serial status and control register	R	0 0 0 0 1 XXX		
32н	SIDR/SODR	Serial input/serial output data register	R/W	XXXXXXXX		
33н	SRC	Serial rate control register	R/W	XXXXXXXX		
34н	IBSR	I <sup>2</sup> C bus status register	R	00000000		
35н	IBCR	I <sup>2</sup> C bus control register	R/W	00011000		
36н	ICCR	I <sup>2</sup> C clock regeister	R/W	0 X 0 XXXXX		
37н	IADR	I <sup>2</sup> C address register	R/W	XXXXXXXX		
<b>38</b> н	IDAR	I <sup>2</sup> C data register	R/W	XXXXXXXX		
39н		Vacancy		1		
ЗАн	SMR1	Serial mode register 1	R/W	00000000		
3Вн	SDR1	Serial data register 1	XXXXXXXX			
3Сн	EIE	External interrupt control register	00000000			
3Dн	EIF	External interrupt flag register	R/W	XXXXXXX 0		
3Ен, 3 <b>F</b> н		Vacancy				
40н	HMDR	HUB mode register	R/W	1 0 XXXXX 0		
<b>41</b> н	HDSR1	Hub descriptor register 1	R/W	XXXXXXXX		
42н	HDSR2	Hub descriptor register 2	R/W	XXXXXXXX		
43н	HDSR3	Hub descriptor register 3	R/W	XXXXXXXX		
44 <sub>H</sub>	HSTR	Hub status register	R/W	00000000		
<b>45</b> н	OCCR	Over current register	R/W	0 XXX 0 0 0 0		
<b>46</b> H	DADR	Descriptor ROM address register	R/W	XXXXXXXX		
<b>47</b> н		Reserved area		1		
48н, 49н		Vacancy				
4Ан	SMR2	Serial mode register 2	R/W	00000000		
<b>4</b> Вн	SDR2	Serial data register 2	R/W	XXXXXXXX		
4Cн, 4Dн		Vacancy				
<b>4</b> Ен	HDSR4	Hub descriptor register 4	R/W	00000101		
<b>4</b> Fн		Vacancy	I	1		
50н	UMDR	USB reset mode register	R/W	1000XX00		
<b>51</b> н	DBAR	DMA base address register	R/W	XXXXXXXX		
52н	TDCR0	Transfer data count register 0	R/W	X0000000		
53н	TDCR1	Transfer data count register 1	R/W	X0000000		
54 <sub>H</sub>		Reserved area	I	1		
55н	TDCR21	Transfer data count register 2	R/W	X0000000		

(Continued)

Address	Register name	Register description	Read/write	Initial value
56н		Reserved area		
57н	TDCR3	Transfer data count register 3	R/W	X000000
<b>58</b> н	UCTR	USB control register	R/W	00000000
<b>59</b> н	USTR1	USB status register 1	R/W	00000000
5Ан	USTR2	USB status register 2	R	XXXXXX 0 0
5Вн	UMSKR	USB interrupt mask register	R/W	00000000
5 <b>С</b> н	UFRMR1	USB frame status register 1	R	XXXXXXXX
5Dн	UFRMR2	USB frame status register 2	R	XXXXXXXX
5Eн	EPER	USB endpoint enable register	R/W	XXXX 0 0 0 1
5Fн	EPBR0	End point setup register 0	R/W	X0000000
60н	EPBR11	Endpoint setup register 11	R/W	XX 0 0 0 0 XX
61н	EPBR12	Endpoint setup register 12	R/W	X0000000
62н	EPBR21	Endpoint setup register 21	R/W	XX 0 0 0 0 XX
63н	EPBR22	Endpoint setup register 22	R/W	X0000000
<b>64</b> ⊦	EPBR31	Endpoint setup register 31	R/W	XX 0 0 0 0 XX
65н	EPBR32	Endpoint setup register 32	R/W	X0000000
66н		Reserved area		
67н to 78н		Vacancy		
<b>79</b> н		Reserved area		
7Ан		Vacancy		
7Вн	ILR1	Interrupt level setting register 1	W	11111111
7Сн	ILR2	Interrupt level setting register 2	W	11111111
7Dн	ILR3	level setting register 3	W	11111111
7Ен	ILR4	Interrupt level setting register 4	W	11111111
7 <b>F</b> н		Reserved area		

 Information about read/write R/W: Read/write enabled, R: Read only, W: Write only

Information about initial values

0: The initial value of this bit is "0".

1: The initial bit of this bit is "1".

X: The initial value of this bit is undefined.

Note : Vacancies and reserved spaces are not for use.

# ■ ELECTRICAL CHARACTERISTICS

### 1. Absolute Maximum Ratings

(Vss = 0 V)

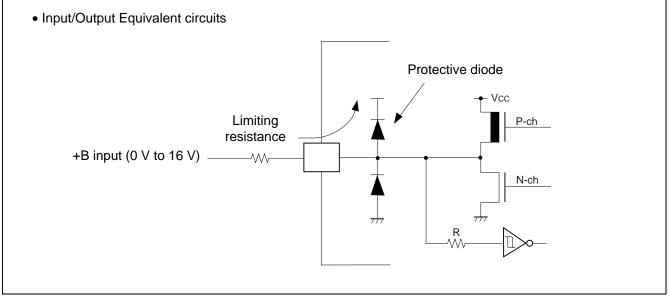
Parameter	Symbol	Rat	ing	Unit	Remarks
Parameter	Symbol	Min	Max	Unit	Remarks
Power supply voltage	Vcc	Vss-0.3	Vss+6.0	V	
		Vss-0.3	Vcc+0.3	V	Other than P31 to P37, P46, P47, P53, P54*1
Input voltage	Vı	Vss-0.3	3.3	V	P31 to P37
		Vss-0.3	Vss+6.0	V	P46,P47,P53, P54*1
		Vss-0.3	Vcc+0.3	V	Other than P31 to P37, P46, P47, P53, P54, CLK1, CLK2, USBP
Output voltage	Vo	Vss-0.3	3.6	V	P31 to P37, CLK1, CLK2, USBP
		Vss-0.3	Vss+6.0	V	P46, P47, P53, 54
Maximum clamp current	CLAMP	-2.0	2.0	mA	*5
Total maximum clamp cuurent	$\Sigma$	_	20	mA	*5
"L" level maximum output current	IOL		15	mA	Normal output*2
"L" level average output current	OLAV	_	4	mA	Normal output*3
"L" level total maximum output current	ΣΙοι	_	100	mA	Total normal output
"L" level total average output current	ΣΙοιαν		40	mA	Total normal output*4
"H" level maximum outputcurrent	Іон		-15	mA	Normal output*2
"H" level average outputcurrent	ОНАУ		-4	mA	Normal output*3
"H" level total maximum output current		_	-50	mA	Total normal output
"H" level maximum outputcurrent	ΣІон	_	-10	mA	Total output of P31 to P37, CLK1, CLK2, USBP.
			-20	mA	Total normal output*4
"H" level average total output currnt	ΣΙοήαν		-10	mA	Total output of P31 to P37, CLK1, CLK2 and USBP.*4
Power consumption	PD		300	mW	
Operating temperature	TA	-40	+85	°C	
Storage temperature	Tstg	-55	+150	°C	

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

\*1: VI should not exceed the specified ratings. However, if the maximum current to /from an input is limited by some means with external components, the ICLAMP rating supersedes the VI rating.

- \*2 : Maximum output current is defined as the peak value at one curresponding pin.
- \*3 : Average output current is defined as the average current flowing through one corresponding pin in an internal of 100 ms. (Average value : operating current × operating duty)

- \*4 : Average total output current is defined as the average current flowing through all corresponding pins in an internal of 100 ms.
- \*5 : Applicable to pins : P00 to P07, P10 to P17, P20 to P27, P40 to P45
  - Use within recommended operating conditions.
  - Use at DC voltage (current)
  - The +B signal should always be applied with a limiting resistance placed between the +B signal and the microcontroller.
  - The value of the limiting resistance should be set so that when the +B signal is applied the input current to the microcontroller pin does not exceed rated values, either instaneously or for prolonged periods.
  - Note that when the microcontroller drive current is low, such as in the power saving modes, the +B input potentional may pass through the protective diode and increase the potentional at the Vcc pin, and this may affect other devices.
  - Note that if a +B signal is input when the microcontroller current is off (not fixed at 0 V), the power supply is provided from the pins, so that incomplete operation may result.
  - Note that if the +B input is applied during power-on, the power supply is provided from the pins and the resulting supply voltage may not be sufficient to operate the power-on result.
  - Care must be taken not to leave the +B input pin open.
  - Note that analog system input pins other than the A/D input pins (LCD drive pins, comparator input pins, etc.) cannot accept +B signl input.
  - Sample recommended circuits :



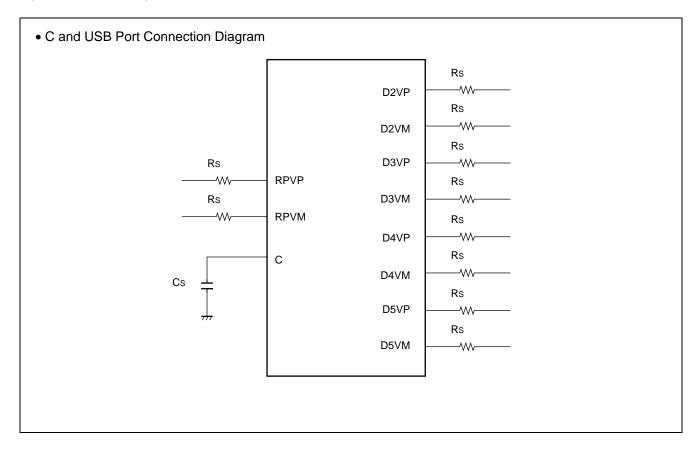
WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

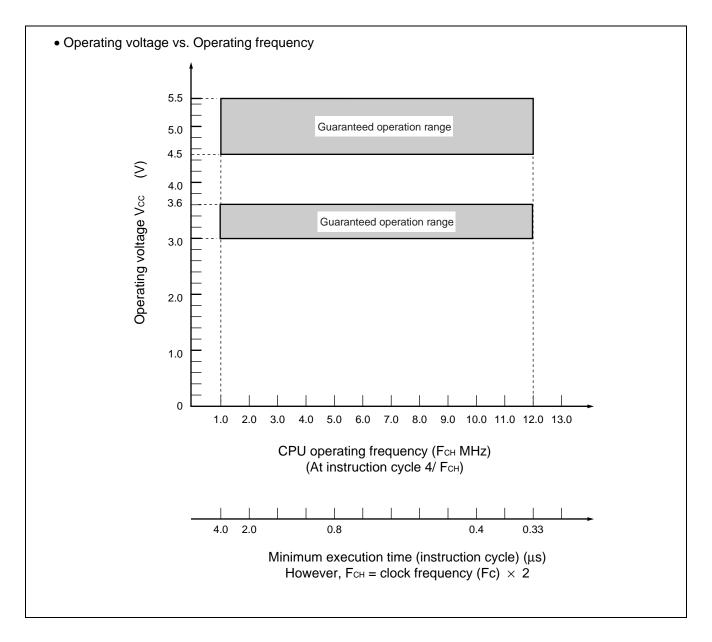
(Vss = 0 V)

### 2. Recommended Operating Conditions

Devementer	Symbol		Value		1.1	Remarks	
Parameter	Symbol	Min	Тур	Max	Unit	Remarks	
Power supply voltage	Maa	4.5	—	5.5	V	At $Vcc = 5.0 V$	
Fower supply voltage	Vcc	3.0	—	3.6	V	At Vcc = 3.3 V*	
	Та	-40	_	+85	°C	When the USB function is not in use.	
Operating temperature		0		+70	°C	When the USB function is in use	
Smoothing capacitor	Cs	0.1	—	1.0	μF	At Vcc = 5.0 V*	
Series resistance	Rs	_	16		Ω	When the USB function is in use	

\*: Use either a ceramic capacitor or a capacitor with similar frequency characteristics. The capacity of the smoothing capacitor for the Vcc pin should be greater than that of the Cs. When using with a supply voltage of 3.3 V, connect pin C with Vcc to input 3.3 V.





WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their FUJITSU representatives beforehand.

# 3. DC Characteristics (Power supply votage : 5.0 V)

(Vcc = 5.0 V, Vss = 0 V, T<sub>A</sub> =  $-40 \text{ }^{\circ}\text{C}$  to  $+85 \text{ }^{\circ}\text{C}$ )

Devementer	Sym	Dim	Condition		Value		11	Remarks
Parameter	bol	Pin	Condition	Min	Тур	Max	Unit	Remarks
"H" level	Vih	P00 to P07, P10 to P17, P20 to P27, P40 to P47, P53, P54, MOD0, MOD1, MOD2		0.7 Vcc		Vcc+0.3	V	
Input voltage		P31 to P37		2.5		3.3	V	3 V
		RST, UCK, UI	_	0.8 Vcc	_	Vcc+0.3	V	
	Vihs	INT1 to INT7, SCK1, SCK2, SI1, SI2		2.9	_	3.3	V	3 V
	VIHI2C	SCL, SDA		0.8 Vcc		Vcc+5.5	V	
	VIL	P00 to P07, P10 to P17, P20 to P27, P40 to P47, P53, P54, MOD0, MOD1, MOD2		Vss-0.3		0.3 Vcc	V	
"L" level Input voltage		P31 to P37		Vss-0.3		0.9		3 V
	VILS	RST, INT1 to INT7, UCK, UI		Vss-0.3		0.2 Vcc	V	
	VILS	INT1 to INT7, SCK1, SCK2, SI1, SI2		Vss-0.3		0.6		3 V
	VILI2C	SCL, SDA		Vss-0.3		0.3 Vcc	V	
Open-drain out- put application voltage	V <sub>D1</sub>	P53, P54	_	Vss-0.3		Vcc+0.3	V	
"H" level	Vон	P00 to P07, P10 to P17, P20 to P24, P40 to P47	Іон = -2.0 mA	4.0	_		V	
Output voltage		P31 to P37, CLK1, CLK2	Іон = -1.0 mA	2.6		3.6 V	V	3 V
		USBP	Iон = -2.4 mA	3.0		3.6 V	V	USB Pull up

(Continued)				(Vcc =	= 5.0 V, V	/ss = 0 V,	$T_A = -$	40 °C to + 85 °C)
Parameter	Sym	Pin	Condition		Value		Unit	Remarks
Falameter	bol	F III	Condition	Min	Тур	Max	Unit	Remarks
"L" level Output voltage	Vol	P00 to P07, P10 to P17, P20 to P24, P40 to P47, P53, P54, RST	lo∟ = 4.0 mA			0.4	V	
		P31 to P37, CLK1, CLK2	lo∟ = 1.0 mA			0.4	V	3 V
Input leakage P2 current P3 (Hi-Z output P4		P00 to P07, P10 to P17, P20 to P27, P31 to P37, P40 to P47,	$0.0 V < V_1 < V_{CC}$	-5		+ 5	μΑ	When no pullup re sistance is speci fied
leakage current)		CLK1, CLK2		-5	_	+ 5	μΑ	
		USBP		-5		+ 5	μΑ	
Open-drain out- put leakage cur- rent	ILIOD	P53, P54	$0.0 V < V_{I} < V_{SS} + 5.5 V$	_	—	+ 5	μA	
Pullup resistance	Rpull	P00 to P07, P10 to P17, P20 to P27, P31 to P37, P40 to P47, P53, P54, RST	V1 = 0.0 V	25	50	100	kΩ	RST is excluded when pullup resistance available is specified.
			Fсн = 12.0 MHz,		29	42	mA	MB89F051
Dower overally	Icc		$\label{eq:Vcc} \begin{array}{l} V_{cc} = 5.0 \ \text{V}, \\ t_{\text{inst}} = 0.333 \ \mu\text{s} \end{array}$		28	41	mA	MB89051
Power supply current	Iccs1	Vcc	$\label{eq:Fch} \begin{split} F_{CH} &= 12.0 \ MHz, \\ V_{CC} &= 5.0 \ V, \\ t_{inst} &= 0.333 \ \mu s \end{split}$	_	20	30	mA	Sleep mode
	Іссн		$T_A= \ +\ 25\ ^\circ C$		40	70	μA	Stop
Input capacitance	CIN	Other than Vcc, Vss and C	f = 1 MHz		5	15	pF	

# 4. DC Characteristics (Power supply votage : 3.3 V)

(Vcc = 3.3 V, Vss = 0 V, T<sub>A</sub> =  $-40 \text{ }^{\circ}\text{C}$  to  $+85 \text{ }^{\circ}\text{C}$ )

Demonstern	Sym	Dia	O and it is a		Value			Demonto
Parameter	bol	Pin	Condition	Min	Тур	Max	Unit	Remarks
"H" level Input voltage	Vih	P00 to P07, P10 to P17, P20 to P27, P31 to P37, P40 to P47, P53, P54, MOD0, MOD1, MOD2	_	0.7 Vcc		Vcc+0.3	V	
	Vihs	RST, UCK, UI, INT1 to INT7, SCK1, SCK2, SI1, SI2	_	0.8 Vcc	_	Vcc+0.3	V	
	VIHI2C	SCL, SDA		0.8 Vcc		Vcc+5.5	V	
"L" level	Vil	P00 to P07, P10 to P17, P20 to P27, P31 to P37, P40 to P47, P53, P54, MOD0, MOD1, MOD2	_	Vss-0.3		0.3 Vcc	V	
Input voltage	Vils	RST, INT1 to INT7, UCK, UI, INT1 to INT7, SCK1, SCK2, SI1, SI2	_	Vss-0.3		0.2 Vcc	V	
	VILI2C	SCL, SDA		Vss-0.3		0.3 Vcc	V	
Open-drain output application voltage	V <sub>D1</sub>	P53, P54	_	Vss-0.3		Vcc+0.3	V	
		P00 to P07, P10 to P17, P20 to P24, P40 to P47	Іон = -2.0 mA	2.6			V	
"H" level Output voltage	Vон	P31 to P37, CLK1, CLK2	Іон = -1.0 mA	2.6			V	
		USBP	Iон = -2.4 mA	3.0			V	USB Pull up, Vcc = 3.1 V to 3.6 V (Continued)

(Continued)

(Vcc = 3.3 V, Vss = 0 V, T<sub>A</sub> =  $-40 \text{ }^{\circ}\text{C}$  to  $+85 \text{ }^{\circ}\text{C}$ )

Parameter	Sym	Pin	Condition		Value		Unit	Remarks
Parameter	bol	PIN	Condition	Min	Тур	Max	Unit	Remarks
"L" level Vo Output voltage		P00 to P07, P10 to P17, P20 to P24, P40 to P47, P53, P54, RST	lo∟ = 4.0 mA			0.4	V	
		P31 to P37, CLK1, CLK2	lo∟ = 1.0 mA			0.4	V	
(HI-2  output   P40  to  P47,	0.0 V < Vı < Vcc	-5		+5	μΑ	When no pullup resistance is specified		
leakage current)		CLK1, CLK2		-5		+5	μΑ	
		USBP		-5		+5	μΑ	
Open-drain output leakage current	ILIOD	P53, P54	0.0 V < V1 < Vss+5.5 V	_		+5	μA	
Pullup resistance	Rpull	P00 to P07, P10 to P17, P20 to P27, P31 to P37, P40 to P47, P53, P54, RST	Vı = 0.0 V	25	50	100	kΩ	RST is excluded when pullup resistance available is specified.
			Fсн = 12.0 MHz,		29	42	mA	MB89F051
Dower currely	Icc		$\label{eq:Vcc} \begin{array}{l} Vcc = 3.3 \ V, \\ t_{\text{inst}} = 0.333 \ \mu s \end{array}$		28	41	mA	MB89051
Power supply current	Iccs1	Vcc	$\label{eq:Fch} \begin{split} F_{CH} &= 12.0 \mbox{ MHz}, \\ V_{CC} &= 3.3 \mbox{ V}, \\ t_{inst} &= 0.333  \mu s \end{split}$		20	30	mA	Sleep mode
	Іссн		T <sub>A</sub> = +25 °C		40	70	μΑ	Stop
Input capacitance	CIN	Other than Vcc and Vss	f = 1 MHz		10		pF	

### 5. AC Characteristics

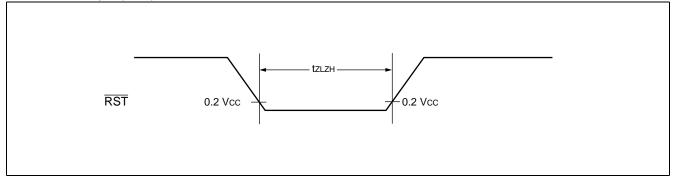
#### (1) Reset Timing

 $(V_{CC} = 5.0 \text{ V}, \text{ Vss} = 0 \text{ V}, \text{ T}_{A} = -40 \text{ }^{\circ}\text{C} \text{ to } +85 \text{ }^{\circ}\text{C})$ 

Parameter	Symbol	Condition	Va	lue	Unit	Remarks	
Farameter	Symbol		Min	Мах	Onic		
RST "L" pulse width	tzlzн		<b>48 t</b> нсγ∟		ns		

Notes : • they is the oscillation cycle for the internal main clock.

If the reset pulse applied to the external reset pin (RST) does not meet the specifications, it may cause
malfunctions. Use caution so that the reset pulse less than the specifications will not be fed to the external
reset pin (RST).



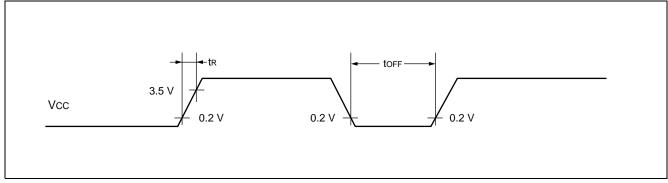
#### (2) Power-on reset

 $(V_{SS} = 0 V, T_A = -40 °C to +85 °C)$ 

Parameter	Symbol	Condition	Va	ue	Unit	Remarks	
			Min	Max	Onit		
Power supply rising time	tR		0.066	50	ms		
Power supply cutoff time	toff		4		ns	Due to repeated operations	

Note : The power supply must be up within the selected oscillation stabilization time.

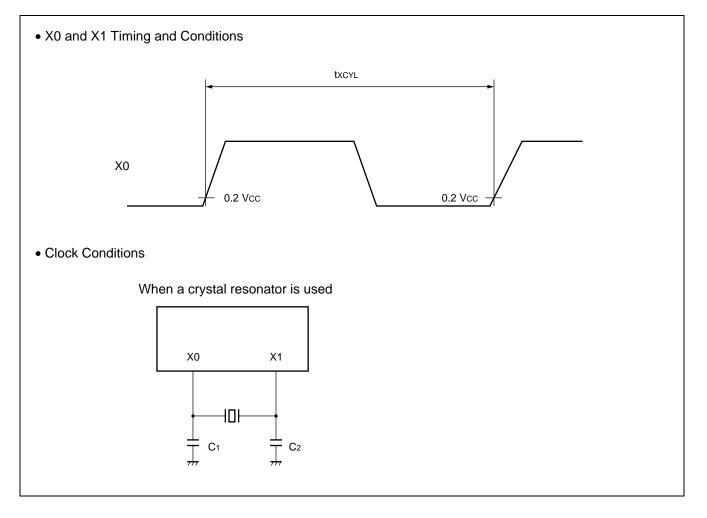
When the supply voltage needs to be varied while operating, it is recommended to smoothly start up the voltage.



### (3) Clock Timing

(Vss = 0 V,  $T_A = -40 \ ^\circ C$  to +85  $^\circ C$ )

Parameter	Symbol	Pin name	Condition		Value		Unit	Remarks
	Symbol	Fininame		Min	Тур	Max	Unit	Reindiks
Clock frequency	Fc	X0, X1			6		MHz	
Clock cycle time	txcyL	X0, X1			166.6	_	ns	
Internal main clock frequency	Fсн	_		_	12	_	MHz	Twice the Fc
Internal clock cycle	<b>t</b> HCYL				83.3		ns	txcyL/2



### (4) Instruction Cycle

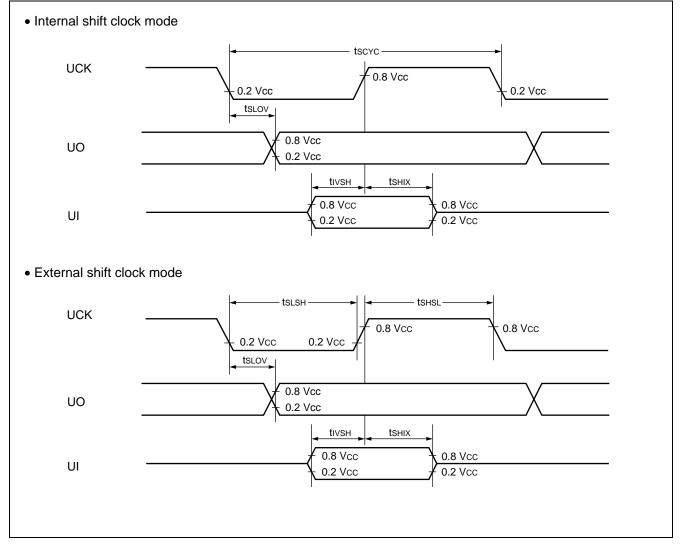
(Vss = 0 V,  $T_A = -40 \ ^{\circ}C$  to +85  $^{\circ}C$ )

Parameter	Symbol	Value	Unit	Remarks
Instruction cycle (Min execution time)	tinst	4 / Есн, 8 / Есн, 16 / Есн, 64 / Есн		When operating at $F_{CH}$ = 12 MHz t <sub>inst</sub> = 0.33 µs (4 / F <sub>CH</sub> )

#### (5) UART Serial I/O Timing

			(V	cc = 5.0 V, V	$v_{ss} = 0 V, T_A$	=−40 °C	C to +85 °C
Parameter	Symbol	Pin name	Condition	Va	lue	Unit	Remarks
Falameter	Symbol		Condition	Min	Max	Unit	Remarks
Serial clock cycle time	tscyc	UCK		2 tinst*		μs	
$UCK \downarrow \to UO$	<b>t</b> slov	UCK, UO	Internal shift clock mode	-200	+200	ns	
Valid UI $\rightarrow$ UCK $\uparrow$	<b>t</b> ivsh	UI, UCK		200	—	ns	
UCK $\uparrow \rightarrow$ valid UI hold time	tsнix	UCK, UI		200	—	ns	
Serial clock "H" pulse width	<b>t</b> s∺s∟	UCK		1 t <sub>inst</sub> *	—	μs	
Serial clock "L" pulse width	<b>t</b> s∟sн	UCK	External	<b>1 t</b> inst*	—	μs	
$UCK \downarrow \to UO \text{ time}$	<b>t</b> sLov	UCK, UO	shift clock	0	200	ns	
Valid UI $\rightarrow$ UCK $\uparrow$	<b>t</b> ivsh	UI, UCK	mode	200		ns	
$UCK \uparrow \to valid \; UI \; hold \; time$	<b>t</b> shix	UCK, UI		200		ns	

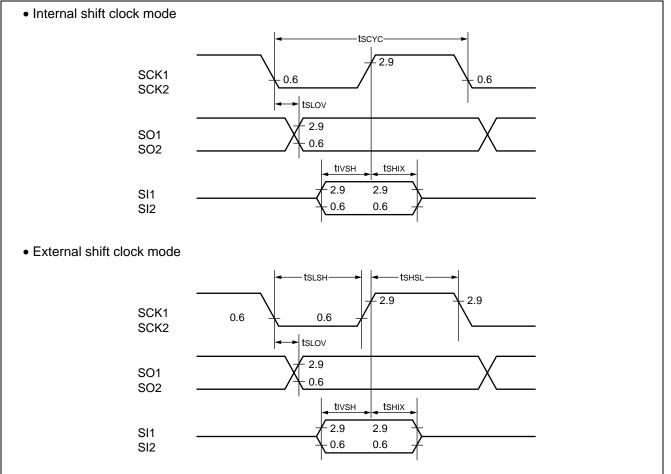
\* : For information on tinst, see " (4) Instruction Cycle".



#### (6) Serial I/O Timing

			(Vo	cc = 5.0 V, V	$ss = 0V, T_A$	= -40 °(	C to +85 °C)
Parameter	Symbol	Pin name	Condition	Value		Unit	Remarks
Falameter	Symbol	Fin hame	Condition	Min	Мах	Unit	IVEIIIdi K3
Serial clock cycle time	<b>t</b> scyc	SCK1, SCK2		2 tinst*		μs	
$SCK \downarrow \to SO \text{ time}$	tslov	SCK1, SO1, SCK2, SO2	Internal	-200	+200	ns	
Valid SI $ ightarrow$ SCK $\uparrow$	tı∨sн	SCK1, SI1, SCK2, SI2	shift clock mode	200		ns	
SCK $\uparrow \rightarrow$ Valid SI hold time	tsнıx	SCK1, SI1, SCK2, SI2		200	_	ns	
Serial clock "H" pulse width	<b>t</b> shsl	SCK1, SCK2		<b>t</b> inst*		μs	
Serial clock "L" pulse width	tslsh	SCK1, SCK2		<b>t</b> inst*		μs	
$SCK \downarrow \to SO$ time	<b>t</b> slov	SCK1, SO1, SCK2, SO2	External shift clock	0	200	ns	
Valid SI $\rightarrow$ SCK	tı∨sн	SCK1, SI1, SCK2, SI2	mode	200		μs	
$SCK \uparrow \to Valid SI hold time$	tsнıx	SCK1, SI1, SCK2, SI2		200		μs	

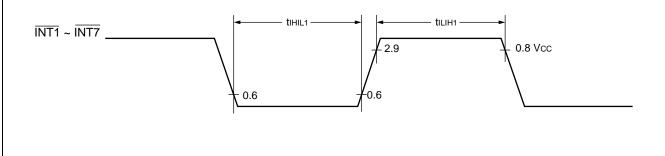
\* : For information on tinst, see " (4) Instruction Cycle".



### (7) Peripheral Input Timing

 $(V_{CC} = 5.0 \text{ V}, \text{ Vss} = 0 \text{ V}, \text{ T}_{A} = -40 \text{ }^{\circ}\text{C} \text{ to } +85 \text{ }^{\circ}\text{C})$ 

Parameter	Symbol	Pin name	Condition	Value		Unit	Remarks
Faiailletei				Min	Max	Unit	Nellia KS
Peripheral input "H" pulse width 1	tı∟ıнı	INT1 to INT7	—	2 tinst*		μs	
Peripheral input "L" pulse width 1	tıнı∟ı		—	2 tinst*		μs	
* : For information on t <sub>inst</sub> , see " (4) Instruction Cycle".							
		<b>↓</b>		—— tu i+1 ——	-1		



### (8) I<sup>2</sup>C Timing

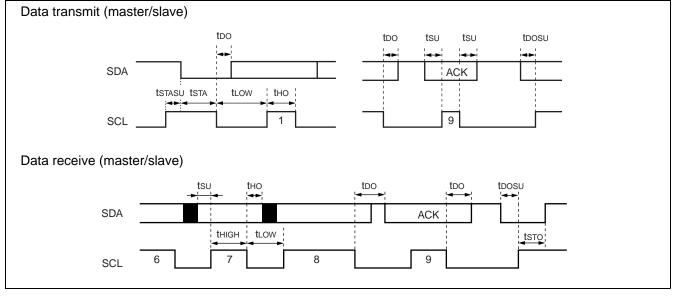
 $(V_{CC} = 5.0 \text{ V}, \text{ V}_{SS} = 0 \text{ V}, \text{ T}_{A} = -40 \text{ }^{\circ}\text{C} \text{ to } +85 \text{ }^{\circ}\text{C})$ 

Parameter	Sym	Pin	Va	l lmit	Remarks	
Farameter	bol	Pin	Min Max			Unit
Start condition output	<b>t</b> sta	SCL, SDA	$\begin{array}{c} 1 \ / \ 4 \times t_{inst}{}^{\star 1} \times \\ m_t{}^{\star} \times n_t{}^{\star 3} - 20 \end{array}$	$\begin{array}{c} 1 \ / \ 4 \times t_{inst}{}^{\star 1} \times \\ m_t{}^{\star 2} \times n_t{}^{\star 3} + 20 \end{array}$	ns	Master mode
Stop condition output	<b>t</b> sto	SCL, SDA	$1 / 4 \times t_{inst}^{*1} \times (m_t^{*2} \times n_t^{*3} + 8) - 20$	$1 / 4 \times t_{inst}^{*1} \times (m_t^{*2} \times n_t^{*3} + 8) + 20$	ns	Master mode
Start condition detect	<b>t</b> sta	SCL, SDA	$1 \ / \ 4 \times t_{\text{inst}}{}^{\star_1} \times 6 + 40$		ns	
Stop condition detect	<b>t</b> sto	SCL, SDA	$1 \ / \ 4 \times t_{\text{inst}}{}^{\star_1} \times 6 + 40$		ns	
Restart condition output	<b>t</b> stasu	SCL, SDA	$\frac{1 / 4 \times t_{inst}{}^{*1} \times}{(m{}^{*2} \times n{}^{*3} + 8) - 20}$	$\frac{1 / 4 \times t_{inst}{}^{*1} \times}{(m_t{}^{*2} \times n_t{}^{*3} + 8) + 20}$	ns	Master mode
Restart condition detect	<b>t</b> stasu	SCL, SDA	$1 \ / \ 4 \times t_{inst}{}^{\star 1} \times 4 + 40$	_	ns	
SCL output Low width	t∟ow	SCL	$\begin{array}{c}1 \ / \ 4 \times t_{inst}{}^{\star 1} \times m_t{}^{\star 2} \times n_t{}^{\star 3} \\ - 20\end{array}$	$\frac{1 / 4 \times t_{inst}^{*1} \times m_t^{*2} \times n_t^{*3}}{+ 20}$	ns	Master mode
SCL output High width	<b>t</b> high	SCL	$\frac{1 / 4 \times t_{inst}{}^{*1} \times}{(m{}^{*2} \times n{}^{*3} + 8) - 20}$	$\frac{1 / 4 \times t_{inst}{}^{*1} \times}{(m_t{}^{*2} \times n_t{}^{*3} + 8) + 20}$	ns	Master mode
SDA output delay	t⊳o	SDA	$1 / 4  imes t_{\text{inst}}^{\star_1}  imes 4 - 20$	$1 / 4  imes t_{inst}^{\star_1}  imes 4 + 20$	ns	
SDA output setup time after interrupt	<b>t</b> DOSU	SDA	$1 \ / \ 4 \times t_{inst}{}^{\star1} \times 4 - 20$		ns	
SCL input Low pulse width	t∟ow	SCL	$1 \ / \ 4 \times t_{inst}{}^{\star_1} \times 6 + 40$		ns	
SCL input High pulse width	<b>t</b> HIGH	SCL	$1 \ / \ 4 \times t_{inst}{}^{\star_1} \times 2 + 40$		ns	
SDA input setup time	<b>t</b> s∪	SDA	40	—	ns	
SDA hold time	tно	SDA	0		ns	

\*1 : For information on tinst, see " (4) Instruction Cycle".

\*2 : m is defined in the ICCR CS 4 to CS 3 (bit 4 to bit 3) .

\*3 : n is defined in the ICCR CS 2 to CS 0 (bit 2 to bit 0) .



# 6. FLASH Program/Erase characteristics

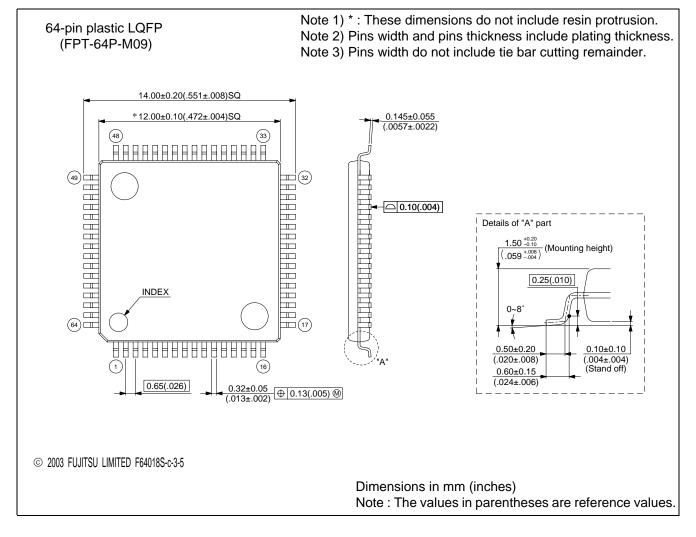
### Program/Erase characteristics

Parameter	Condition		Value		Unit	Remarks
Farameter	Condition	Min	Тур	Max	Onit	Remarks
Sector erase time		_	1	15	S	Except for the write time before internal erase operation
Chip erase time	T <sub>A</sub> = +25 °C Vcc = 5.0 V		5	75	S	Except for the write time before internal erase operation
Byte program time			8	3,600	μs	Except for the over head time of the system.
Prgram/erase cycle		10,000			cycle	

# ■ ORDERING INFORMATION

Part Number	Package	Remarks
MB89051PFM MB89F051PFM	64-pin plastic LQFP (FPT-64P-M09)	

### ■ PACKAGE DIMENSIONS



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